Hex Buffer

The MC14049B Hex Inverter/Buffer and MC14050B Noninverting Hex Buffer are constructed with MOS P—Channel and N—Channel enhancement mode devices in a single monolithic structure. These complementary MOS devices find primary use where low power dissipation and/or high noise immunity is desired. These devices provide logic level conversion using only one supply voltage, VDD.

The input–signal high level (V_{IH}) can exceed the V_{DD} supply voltage for logic level conversions. Two TTL/DTL loads can be driven when the devices are used as a CMOS–to–TTL/DTL converter (V_{DD} = 5.0 V, V_{OL} \leq 0.4 V, I_{OL} \geq 3.2 mA).

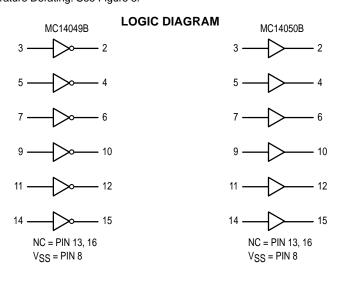
Note that pins 13 and 16 are not connected internally on these devices; consequently connections to these terminals will not affect circuit operation.

- High Source and Sink Currents
- High-to-Low Level Converter
- Supply Voltage Range = 3.0 V to 18 V
- V_{IN} can exceed V_{DD}
- Meets JEDEC B Specifications
- Improved ESD Protection On All Inputs

$\textbf{MAXIMUM RATINGS} \textbf{1} \text{ (Voltages Referenced to V}_{SS} \textbf{)}$

| Characteristic | Symbol | Value | Unit |
|--|------------------|--------------------------|------|
| DC Supply Voltage | V_{DD} | - 0.5 to + 18.0 | Vdc |
| Input Voltage (DC or Transient) | VIN | - 0.5 to + 18.0 | Vdc |
| Output Voltage (DC or Transient) | V _{out} | -0.5 to $V_{DD} + 0.5$ | Vdc |
| Input Current (DC or Transient), per Pin | l _{in} | ± 10 | mA |
| Output Current (DC or Transient), per Pin | l _{out} | + 45 | mA |
| Power Dissipation, per Package ² (Plastic/Ceramic) (SOIC) | PD | 825 740 | mW |
| Storage Temperature | T _{stg} | - 65 to + 150 | °C |
| Lead Temperature (8 – Second Soldering) | TL | 260 | °C |

¹ Maximum Ratings are those values beyond which damage to the device may occur. 2 Temperature Derating: See Figure 3.



MC14049B MC14050B



L SUFFIX CERAMIC CASE 620



P SUFFIX PLASTIC CASE 648



D SUFFIX SOIC CASE 751B

ORDERING INFORMATION

MC14XXXBCP Plastic
MC14XXXBCL Ceramic
MC14XXXBD SOIC

 $T_{\Delta} = -55^{\circ}$ to 125°C for all packages.

PIN ASSIGNMENT 16 H NC V_{DD} [] 1 ● OUT_A 15 DOUTE 14 | IN_F IN_A OUTB [13 NC 12 0UT_F IN_R [] 5 OUT_C [6 11 | IN_F IN_C [7 10 DOUTD 9 | IND V_{SS} [] 8



ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

| | | | V _{DD} | - 5 | 5°C | | + 25°C | | + 12 | .5°C | |
|---|-----------|------------------|-----------------|-------------------------|----------------------|----------------------------|--|----------------------|-------------------------|----------------------|------|
| Characterist | ic | Symbol | Vdc | Min | Max | Min | Typ ¹ | Max | Min | Max | Unit |
| Output Voltage V _{in} = V _{DD} | "0" Level | VOL | 5.0 10 15 | _ _ _ | 0.05 0.05 0.05 | _ _ _ | 0 0 0 | 0.05 0.05 0.05 | _ _ | 0.05 0.05 0.05 | Vdc |
| V _{in} = 0 | "1" Level | VOH | 5.0 10 15 | 4.95 9.95 14.95 | _ _ _ | 4.95 9.95 14.95 | 5.0 10 15 | _ _ _ | 4.95 9.95 14.95 | _ _ _ | Vdc |
| Input Voltage (V _O = 4.5 Vdc) (V _O = 9.0 Vdc) (V _O = 13.5 Vdc) | "0" Level | V _I L | 5.0 10 15 | _ _ _ | 1.5 3.0 4.0 | _ _ _ | 2.25 4.50 6.75 | 1.5 3.0 4.0 | _ _ _ | 1.5 3.0 4.0 | Vdc |
| (V _O = 0.5 Vdc) (V _O = 1.0 Vdc) (V _O = 1.5 Vdc) | "1" Level | VIH | 5.0 10 15 | 3.5 7.0 11 | _ _ _ | 3.5 7.0 11 | 2.75 5.50 8.25 | _ _ _ | 3.5 7.0 11 | | Vdc |
| Output Drive Current (V _{OH} = 2.5 Vdc) (V _{OH} = 9.5 Vdc) (V _{OH} = 13.5 Vdc) | Source | Іон | 5.0 10 15 | - 1.6 - 1.6 - 4.7 | _ _ _ | - 1.25 - 1.30 - 3.75 | - 2.5 - 2.6 - 10 | _ _ _ | - 1.0 - 1.0 - 3.0 | = | mAdc |
| (V _{OL} = 0.4 Vdc) (V _{OL} = 0.5 Vdc) (V _{OL} = 1.5 Vdc) | Sink | lOL | 5.0 10 15 | 3.75 10 30 | _ _ _ | 3.2 8.0 24 | 6.0 16 40 | _ _ | 2.6 6.6 19 | _ _ _ | mAdc |
| Input Current | | l _{in} | 15 | _ | ± 0.1 | _ | ±0.00001 | ± 0.1 | _ | ± 1.0 | μAdc |
| Input Capacitance (Vin | = 0) | C _{in} | _ | _ | _ | _ | 10 | 20 | | _ | pF |
| Quiescent Current (Per | Package) | I _{DD} | 5.0 10 15 | _ _ _ | 1.0 2.0 4.0 | _ _ _ | 0.002 0.004 0.006 | 1.0 2.0 4.0 | _ _ _ | 30 60 120 | μAdc |
| Total Supply Current 2,3 (Dynamic plus Quies per package) (C _L = 50 pF on all of buffers switching | scent, | lΤ | 5.0 10 15 | | | $I_{T} = (3$ | .8 μΑ/kHz) f β.5 μΑ/kHz) f δ.3 μΑ/kHz) f | + IDD | | | μAdc |

¹ Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) \text{ Vfk}$$

Where: I_T is in μA (per Package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency and k = 0.002.

This device contains protection circuitry to protect the inputs against damage due to high static voltages or electric fields referenced to the VSS pin only. Extra precautions must be taken to avoid applications of any voltage higher than the maximum rated voltages to this high-impedance circuit. For proper operation, the ranges $V_{SS} \leq V_{in} \leq 18 \text{ V}$ and $V_{SS} \leq V_{out} \leq V_{DD}$ are recommended.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either VSS or VDD). Unused outputs must be left open.

² The formulas given are for the typical characteristics only at + 25°C

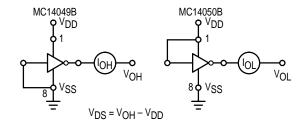
³ To calculate total supply current at loads other than 50 pF:

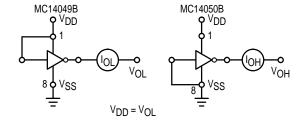
AC SWITCHING CHARACTERISTICS 1 ($C_L = 50 \text{ pF}, T_A = +25^{\circ}\text{C}$)

| Characteristic | Symbol | V _{DD} Vdc | Min | Typ ² | Max | Unit |
|---|------------------|------------------------|-------------|------------------|-----------------|------|
| Output Rise Time $t_{TLH} = (0.7 \text{ ns/pF}) \text{ C}_{L} + 65 \text{ ns}$ $t_{TLH} = (0.25 \text{ ns/pF}) \text{ C}_{L} + 37.5 \text{ ns}$ $t_{TLH} = (0.2 \text{ ns/pF}) \text{ C}_{L} + 30 \text{ ns}$ | ^t TLH | 5.0 10 15 | <u> </u> | 100 50 40 | 160 80 60 | ns |
| Output Fall Time t _{THL} = (0.2 ns/pF) C _L + 30 ns t _{THL} = (0.06 ns/pF) C _L + 17 ns t _{THL} = (0.04 ns/pF) C _L + 13 ns | ^t THL | 5.0 10 15 | _ _ _ | 40 20 15 | 60 40 30 | ns |
| Propagation Delay Time tpLH = (0.33 ns/pF) C _L + 63.5 ns tpLH = (0.19 ns/pF) C _L + 30.5 ns tpLH = (0.06 ns/pF) C _L + 27 ns | ^t PLH | 5.0 10 15 | _ _ _ | 80 40 30 | 140 80 60 | ns |
| Propagation Delay Time tpHL = (0.2 ns/pF) C _L + 30 ns tpHL = (0.1 ns/pF) C _L + 15 ns tpHL = (0.05 ns/pF) C _L + 12.5 ns | [†] PHL | 5.0 10 15 | | 40 20 15 | 80 40 30 | ns |

¹ The formulas given are for the typical characteristics only at 25°C.

² Data labeled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.





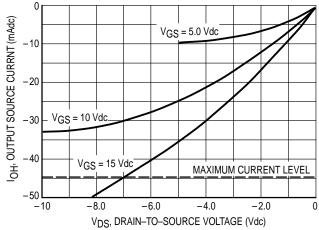


Figure 1. Typical Output Source Characteristics

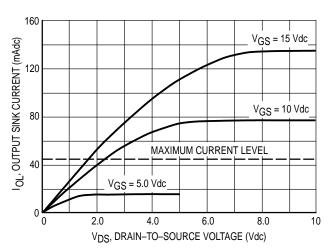


Figure 2. Typical Output Sink Characteristics

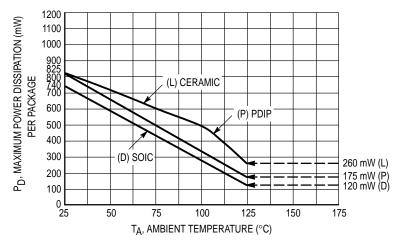


Figure 3. Ambient Temperature Power Derating

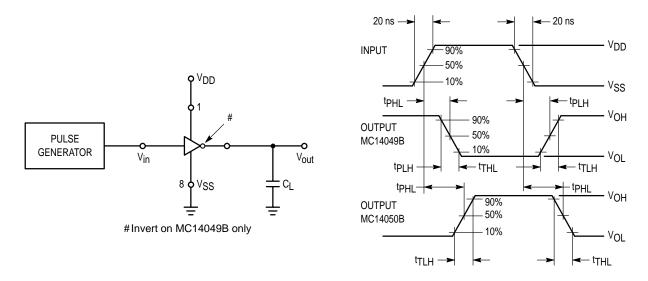
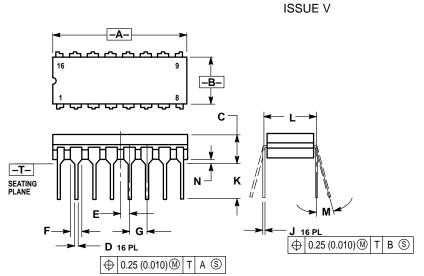


Figure 4. Switching Time Test Circuit and Waveforms

OUTLINE DIMENSIONS

L SUFFIX CERAMIC DIP PACKAGE CASE 620-10



NOTES:

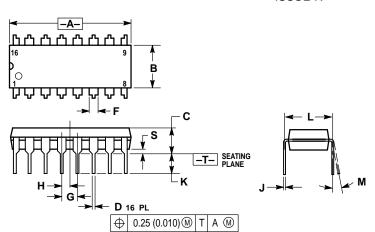
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

- ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 DIMENSION L TO CENTER OF LEAD WHEN
 FORMED PARALLEL.
 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC

| | INCHES | | MILLIMETERS | | |
|-----|--------|-----------|-------------|-------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 0.750 | 0.785 | 19.05 | 19.93 | |
| В | 0.240 | 0.295 | 6.10 | 7.49 | |
| C | | 0.200 | | 5.08 | |
| D | 0.015 | 0.020 | 0.39 | 0.50 | |
| Е | 0.050 | 0.050 BSC | | BSC | |
| F | 0.055 | 0.065 | 1.40 | 1.65 | |
| G | 0.100 | 0.100 BSC | | BSC | |
| Н | 0.008 | 0.015 | 0.21 | 0.38 | |
| K | 0.125 | 0.170 | 3.18 | 4.31 | |
| L | 0.300 | 0.300 BSC | | BSC | |
| M | 0 ° | 15° | 0 ° | 15° | |
| N | 0.020 | 0.040 | 0.51 | 1.01 | |

P SUFFIX

PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

| | INC | HES | MILLIMETERS | | | |
|-----|-------|-------|-------------|-------|--|--|
| DIM | MIN | MAX | MIN | MAX | | |
| Α | 0.740 | 0.770 | 18.80 | 19.55 | | |
| В | 0.250 | 0.270 | 6.35 | 6.85 | | |
| С | 0.145 | 0.175 | 3.69 | 4.44 | | |
| D | 0.015 | 0.021 | 0.39 | 0.53 | | |
| F | 0.040 | 0.70 | 1.02 | 1.77 | | |
| G | 0.100 | BSC | 2.54 BSC | | | |
| Н | 0.050 | BSC | 1.27 BSC | | | |
| J | 0.008 | 0.015 | 0.21 | 0.38 | | |
| K | 0.110 | 0.130 | 2.80 | 3.30 | | |
| L | 0.295 | 0.305 | 7.50 | 7.74 | | |
| M | 0° | 10° | 0° | 10 ° | | |
| S | 0.020 | 0.040 | 0.51 | 1.01 | | |

OUTLINE DIMENSIONS



- DIMENSIONING AND TOLERANCING PER ANSI
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

 MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| | MILLIN | IETERS | INCHES | | |
|-----|----------|--------|-----------|-------|--|
| DIM | MIN MAX | | MIN | MAX | |
| Α | 9.80 | 10.00 | 0.386 | 0.393 | |
| В | 3.80 | 4.00 | 0.150 | 0.157 | |
| С | 1.35 | 1.75 | 0.054 | 0.068 | |
| D | 0.35 | 0.49 | 0.014 | 0.019 | |
| F | 0.40 | 1.25 | 0.016 | 0.049 | |
| G | 1.27 BSC | | 0.050 BSC | | |
| J | 0.19 | 0.25 | 0.008 | 0.009 | |
| K | 0.10 | 0.25 | 0.004 | 0.009 | |
| M | 0° | 7° | 0° | 7° | |
| Р | 5.80 | 6.20 | 0.229 | 0.244 | |
| R | 0.25 | 0.50 | 0.010 | 0.019 | |

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